

Sync Signal Generator for Camera

Description

The CXD1159AQ is a sync signal generator for consumer video cameras.

Features

- Adapts to NTSC or PAL through mode switching
- Low power consumption
- Phase comparator and built-in inverter for active filter (Power supply according to inverter for filter)
- Supports external synchronization

Structure

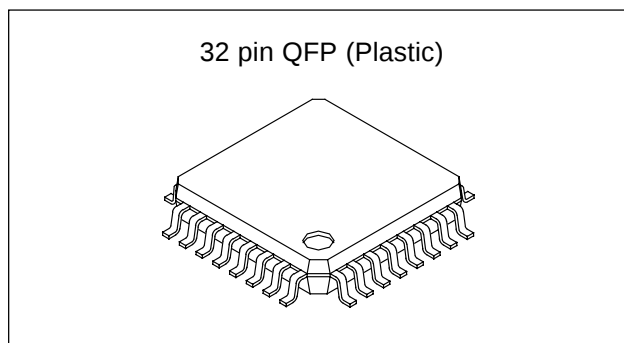
Silicon gate CMOS

Application

Video cameras

Functions

Generation of various sync signals



Absolute Maximum Ratings (Ta = 25°C)

• Supply voltage	V _{DD}	V _{SS} *1 – 0.5 to +7.0	V
• Input voltage	V _I	V _{SS} *1 – 0.5 to V _{DD} + 0.5	V
• Output voltage	V _O	V _{SS} *1 – 0.5 to V _{DD} + 0.5	V
• Storage temperature	T _{stg}	–55 to +150	°C

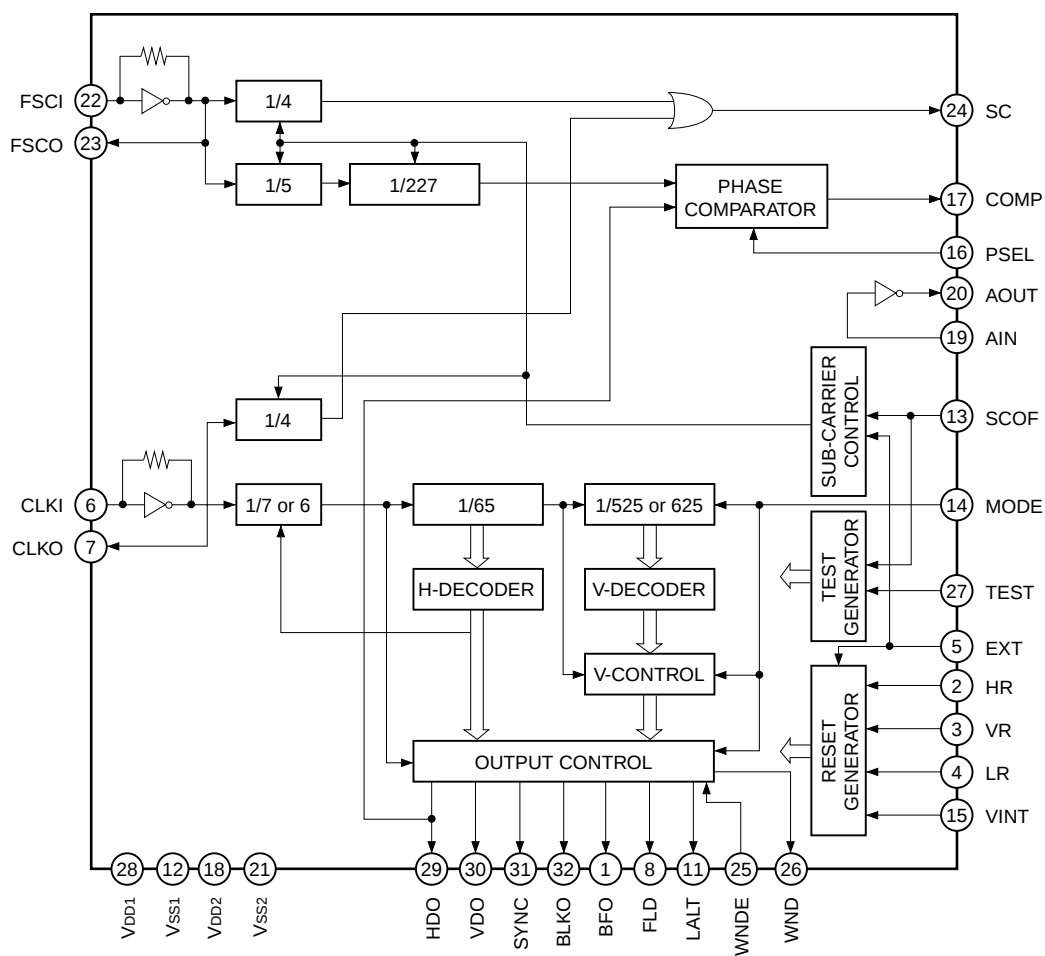
*1 V_{SS} = 0V

Recommended Operating Conditions

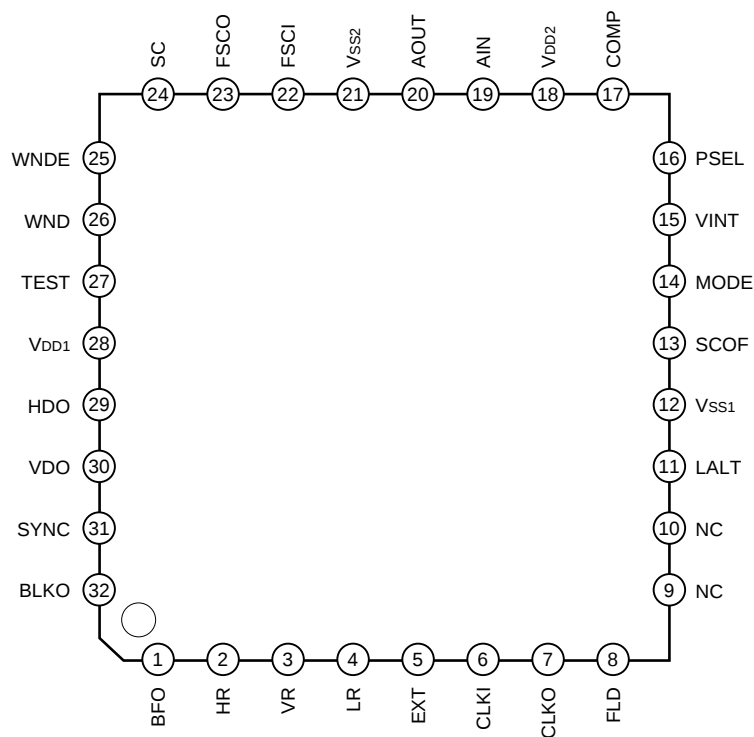
• Supply voltage	V _{DD}	4.50 to 5.50	V
• Operating temperature	T _{opr}	–20 to +75	°C

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Block Diagram



Pin Configuration



Pin Description

Pin No.	Symbol	I/O	Description
1	BFO	O	Burst flag pulse
2	HR	I	H reset input
3	VR	I	V reset input
4	LR	I	LALT reset input
5	EXT	I	Internal/External mode switching $\overline{\text{INT}}/\text{EXT}$
6	CLKI	I	Clock input (NTSC: 14.31818MHz, PAL: 14.1875MHz)
7	CLKO	O	Clock output
8	FLD	O	Field pulse
9	NC	—	
10	NC	—	
11	LALT	O	Line alternate pulse
12	V _{SS1}	—	GND
13	SCOF	I	Sub carrier suppress input L: OFF
14	MODE	I	NTSC/PAL mode switching $\overline{\text{NTSC}}/\text{PAL}$
15	VINT	I	Initialize input
16	PSEL	I	Phase comparator polarity switch
17	COMP	O	Phase comparator output
18	V _{DD2}	—	Filter inverter +5V
19	AIN	I	Filter inverter input
20	AOUT	O	Filter inverter output
21	V _{SS2}	—	Filter inverter GND
22	FSCI	I	4fsc clock input
23	FSCO	O	4fsc clock output
24	SC	O	Sub carrier output
25	WNDE	I	WND output enable input (at L: Enable)
26	WND	O	Window output
27	TEST	I	Test input (Normally "L")
28	V _{DD1}	—	+5V
29	HDO	O	Horizontal drive pulse
30	VDO	O	Vertical drive pulse
31	SYNC	O	Composite sync pulse
32	BLKO	O	Composite blanking pulse

Electrical Characteristics

DC Characteristics

(V_{DD} = 5V ± 10%, V_{SS} = 0V, T_{opr} = –20 to +75°C)

Item		Symbol	Conditions	Min.	Typ.	Max.	Unit
Supply current		I _{DD}			4.5		mA
		I _{DDS}	Static state*1	0		0.1	mA
Output voltage I*2	High level	V _{OH}	I _{OH} = –2mA	V _{DD} – 0.8		V _{DD}	V
	Low level	V _{OL}	I _{OL} = 4mA	V _{SS}		0.4	V
Output voltage II*3	High level	V _{OH}	I _{OH} = –1.5mA	V _{DD} /2		V _{DD}	V
	Low level	V _{OL}	I _{OL} = 1.5mA	V _{SS}		V _{DD} /2	V
Input voltage	High level	V _{IH}		0.7V _{DD}			V
	Low level	V _{IL}				0.3V _{DD}	V
Input leak current		I _{LI}	V _I = 0V to V _{DD}	–10		10	μA
Input leak current*4		I _{LZ}		–10		10	μA

*1 V_{IH} = V_{DD}, V_{IL} = V_{SS}

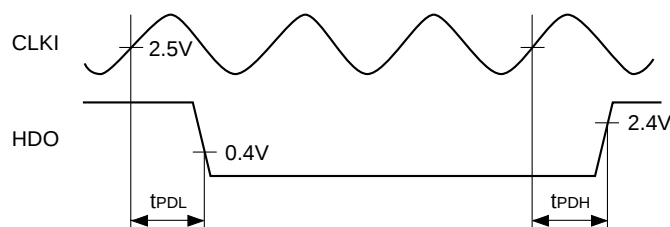
*2 Output pins except "AOUT"

*3 "AOUT" pin

*4 Tri-state pin

AC Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Fall delay time	t _{PDL}	V _{OL} = 0.4V			45	ns
Rise delay time	t _{PDH}	V _{OH} = 2.4V			45	ns



I/O Capacitance

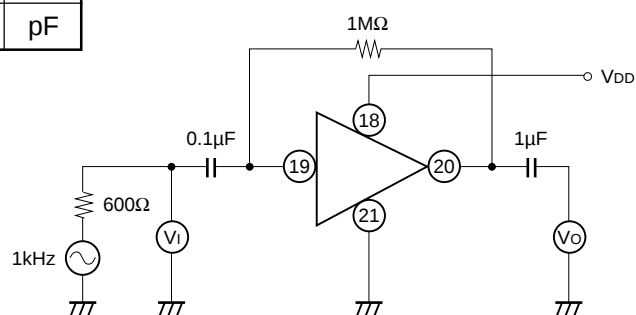
Item	Symbol	Min.	Typ.	Max.	Unit
Input pin	C _{IN}			9	pF
Output pin	C _{OUT}			11	pF

Test conditions: V_{DD} = V_I = 0V, f_M = 1MHz

Filter Amplifier Characteristics

Voltage gain G_v 25dB (Typ.)

Test Circuit



$$G_v = 20 \log \frac{V_O}{V_I}$$

Functions

1. Generation of various sync signals (See the Timing Chart.)

Various sync signals are generated from clocks.

- Clock frequencies

NTSC: $910f_H$ (14.31818MHz)

PAL: $908f_H$ (14.1875MHz)

$4f_{sc}$ (17.734475MHz)

For the system clock

NTSC: $910f_H/7$

PAL: $908f_H/7$ or 6

2. PAL PLL for $4f_{sc}$

To the master clock of $908f_H$ is matched a phase of $4f_{sc}$. The polarity of the phase comparator can be switched according to the type of external filter (passive or active).

Filter	PSEL	Master ($908f_H$)	$4f_{sc}$	COMP
Passive	L	Fast	Delay	H
		Slow	Fast	L
Active	H	Fast	Delay	L
		Slow	Fast	H

3. SC (Sub-Carrier) generation

Mode	INT or EXT	SC
NTSC	INT	$910f_H/4$
NTSC	EXT	$4f_{sc}/4$
PAL	x	$4f_{sc}/4$

INT: Internal mode

(EXT = L)

EXT: External mode

(EXT = H)

In either mode unused counters are stopped. When SC is not required, by setting SCOF to L all SC counters are stopped and SC is not output.

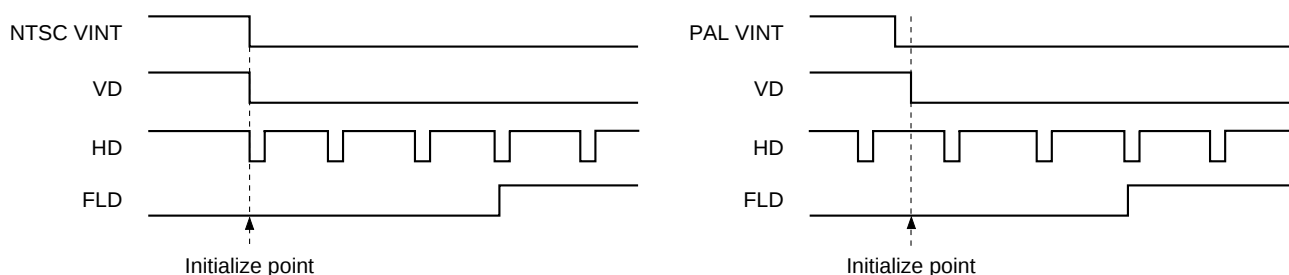
4. Initialization and Reset

In INT mode the circuit is initialized with the fall of VINT. At that time, H, V and LALT resets are not accepted.

In EXT mode, VINT is not accepted, whereas H, V and LALT resets are accepted.

• Initialize (VINT)

When EXT = L, VINT fall is detected and operation is started as the circuit is initialized at the VD fall position just before field I. (Initialization is completed within 100ns after the fall is detected).

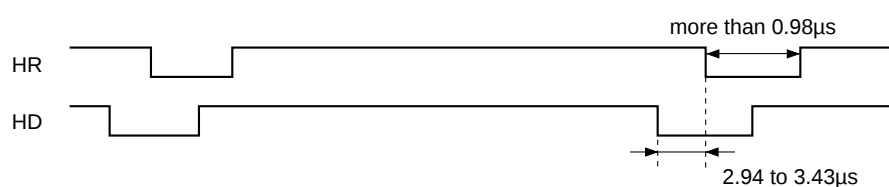


• H reset (HR)

Reset is performed with the first fall. However reset is not done anymore unless there is a deviation of more than 2 clocks ($0.98\mu\text{s}$) to the subsequent edges.

The minimum reset pulse width is $0.98\mu\text{s}$.

HD is reset 2.94 to $3.43\mu\text{s}$ in advance of HR input.



• V reset (VR)

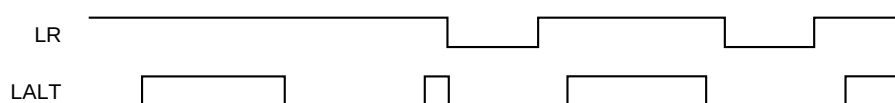
VD is reset 3.5H in advance of VR input.

The minimum reset pulse width is $32\mu\text{s}$.

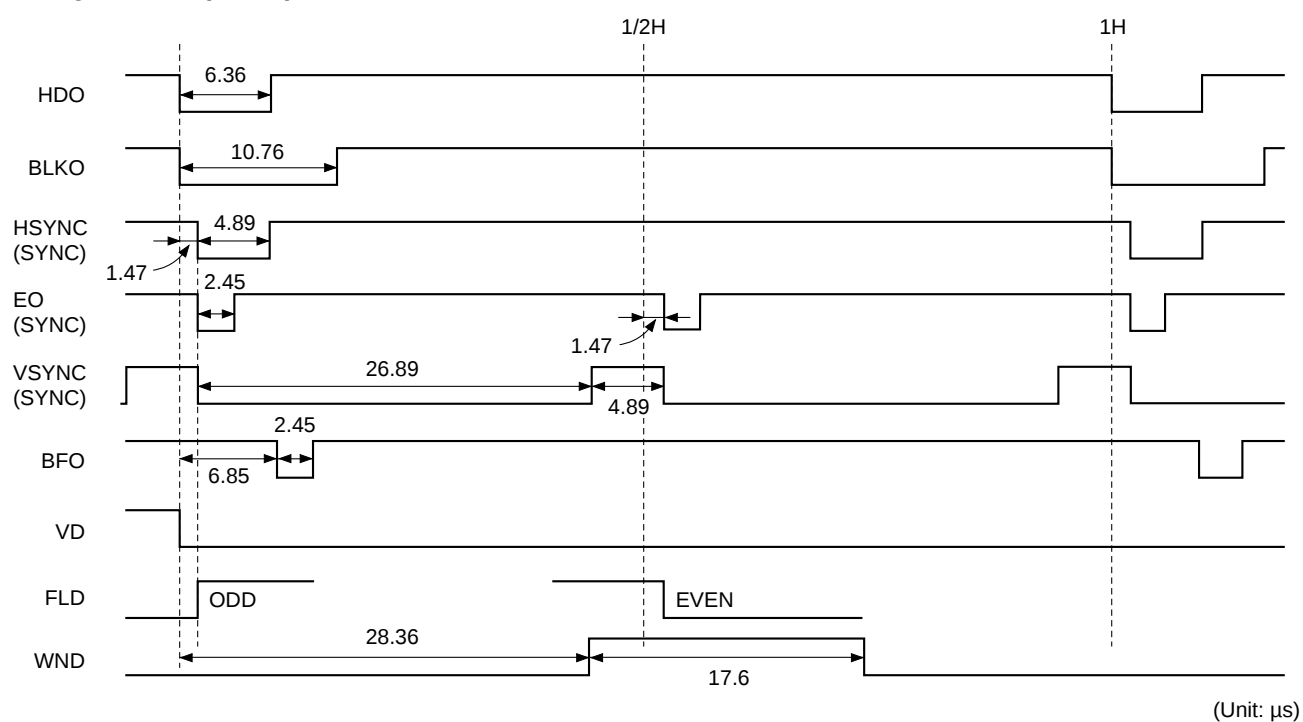
• LALT reset (LR)

LALT is reset in the same phase as LR reset.

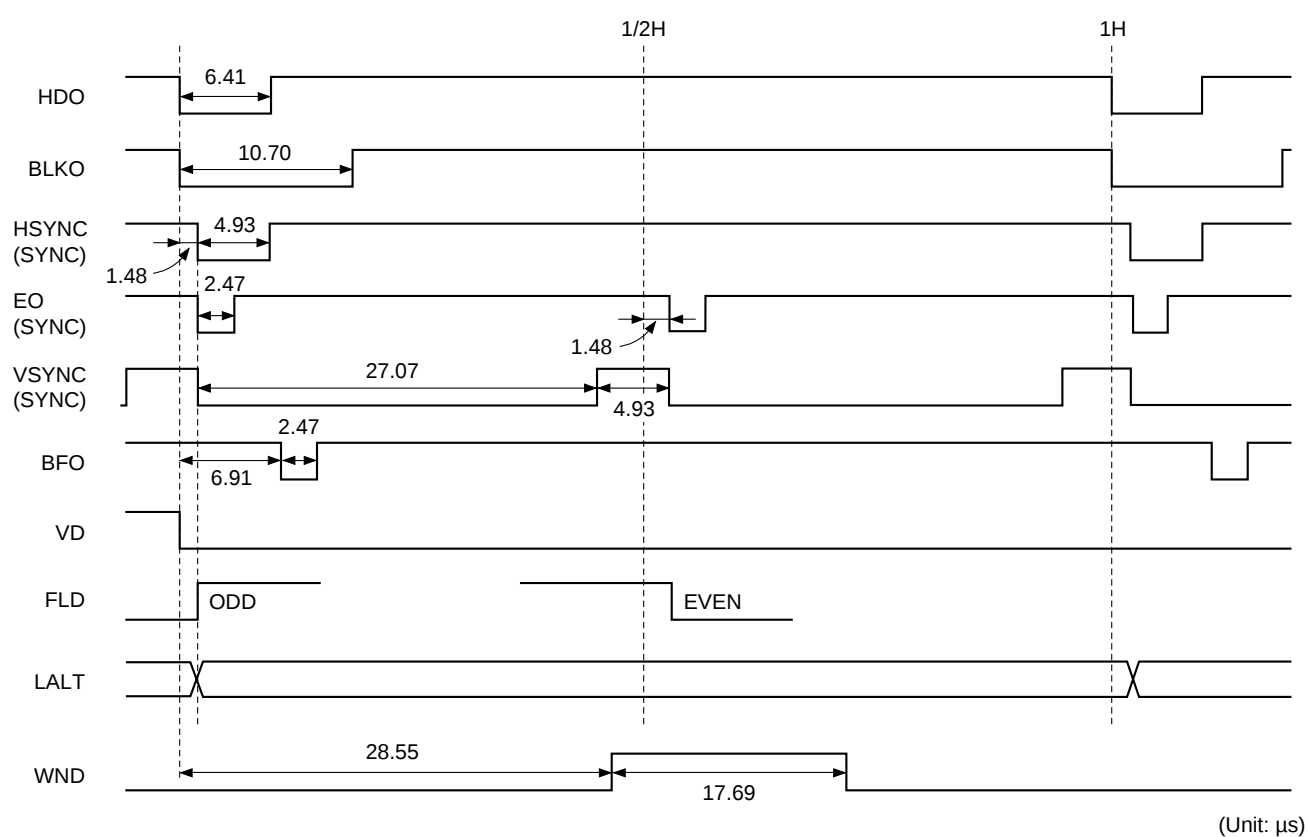
The minimum reset pulse width is $32\mu\text{s}$.



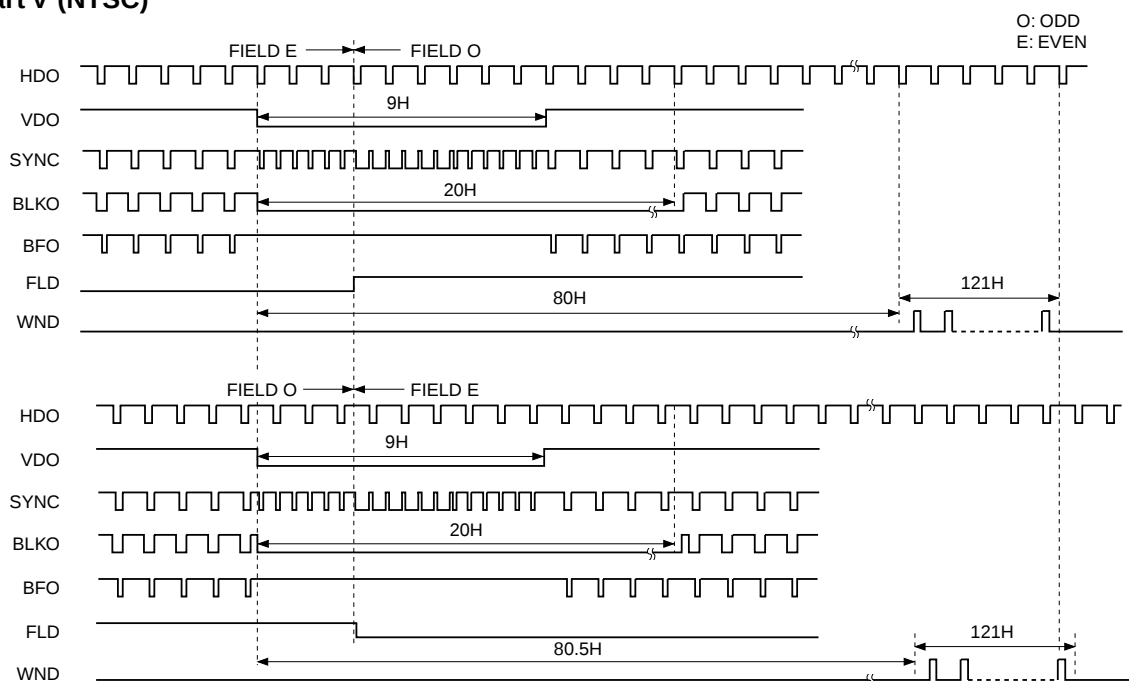
Timing Chart H (NTSC)



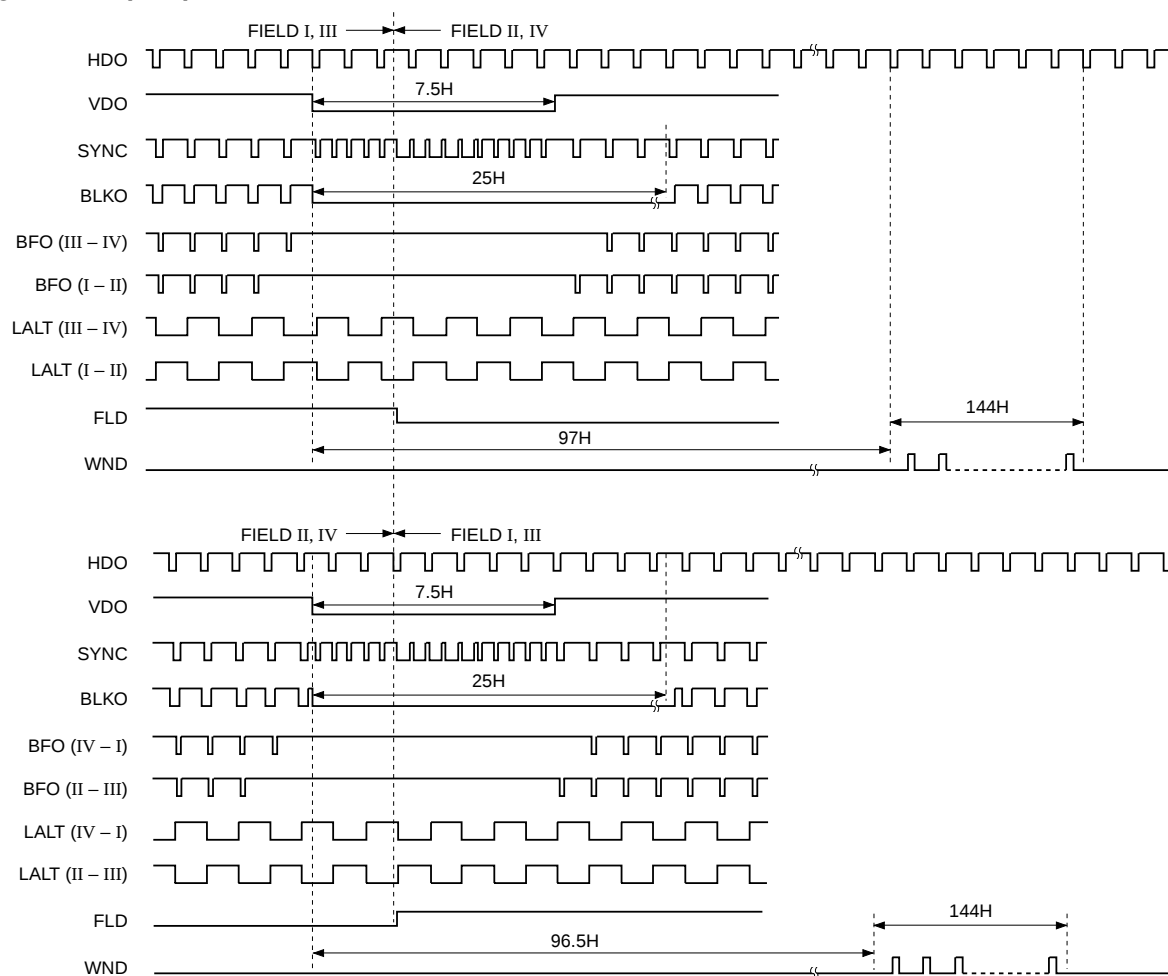
Timing Chart H (PAL)



Timing Chart V (NTSC)

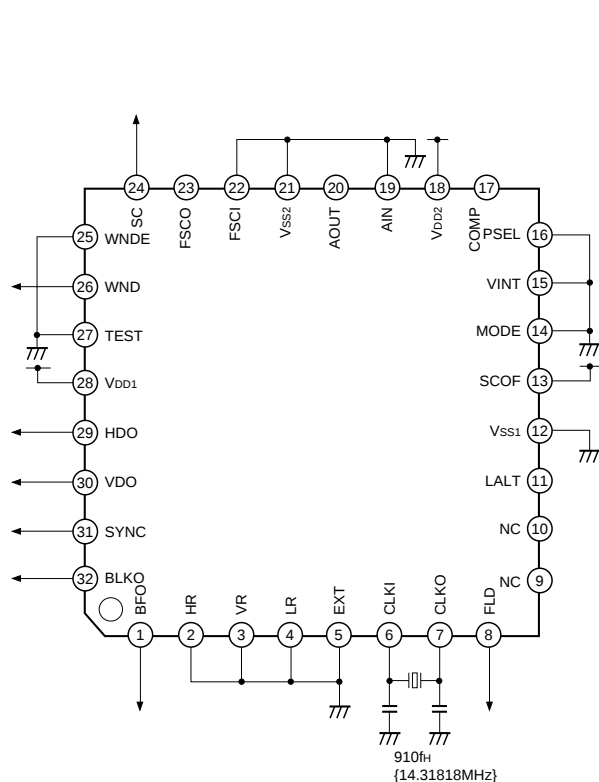


Timing Chart V (PAL)

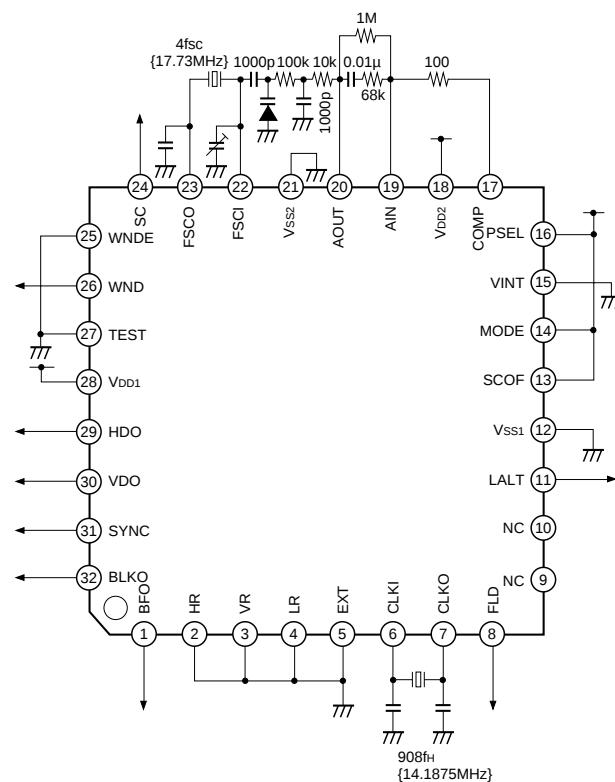


Application Circuit

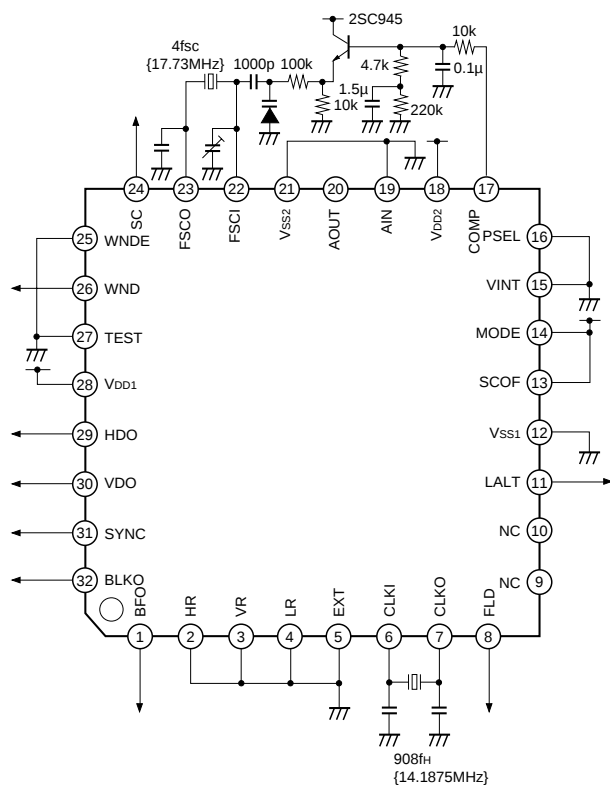
NTSC (Internal mode)



PAL (Filter configuration 1, Internal mode)



PAL (Filter configuration 2, Internal mode)

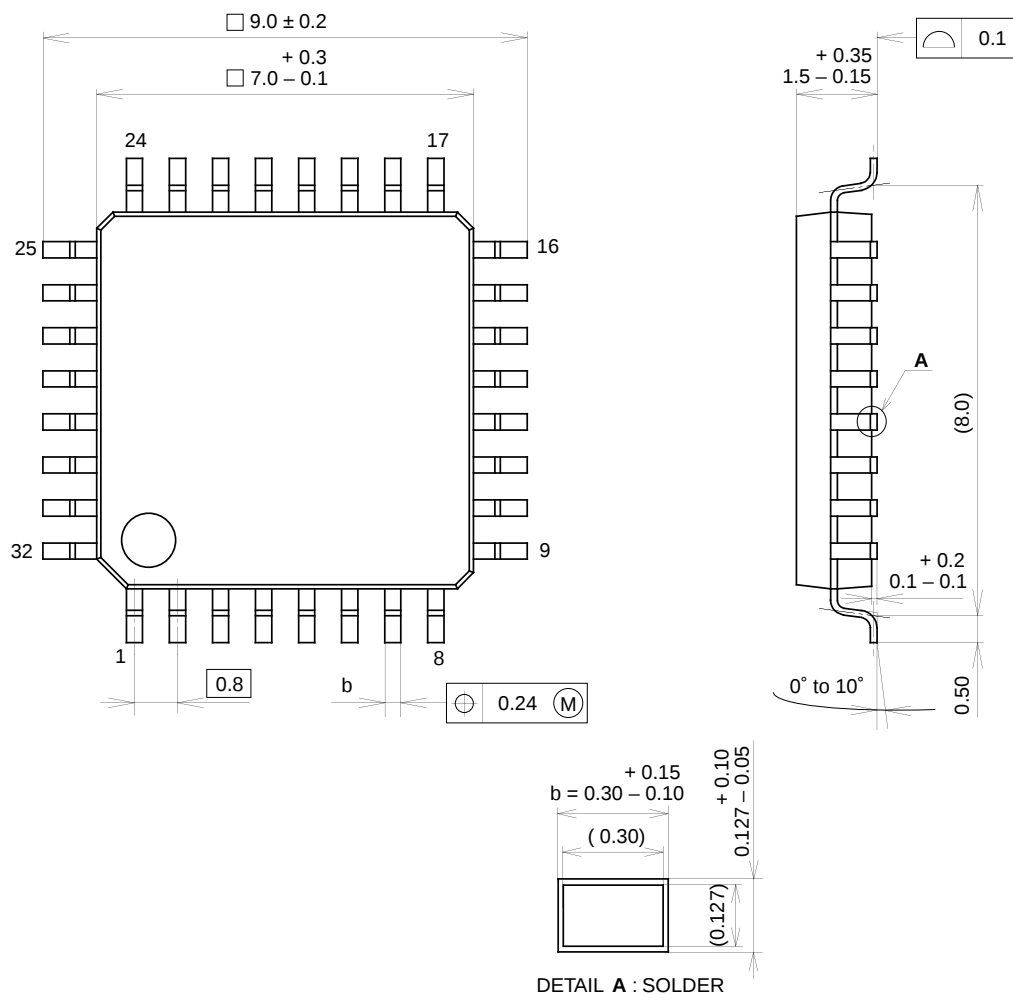


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Package Outline

Unit: mm

32PIN QFP (PLASTIC)



SONY CODE	QFP-32P-L01
EIAJ CODE	P-QFP32-7x7-0.8
JEDEC CODE	_____

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42 / COPPER ALLOY
PACKAGE MASS	0.2g

LEAD SPECIFICATIONS

ITEM	SPEC.
LEAD MATERIAL	ALLOY 42
LEAD TREATMENT	Sn-Pb 10%
LEAD TREATMENT THICKNESS	5-18 μ m